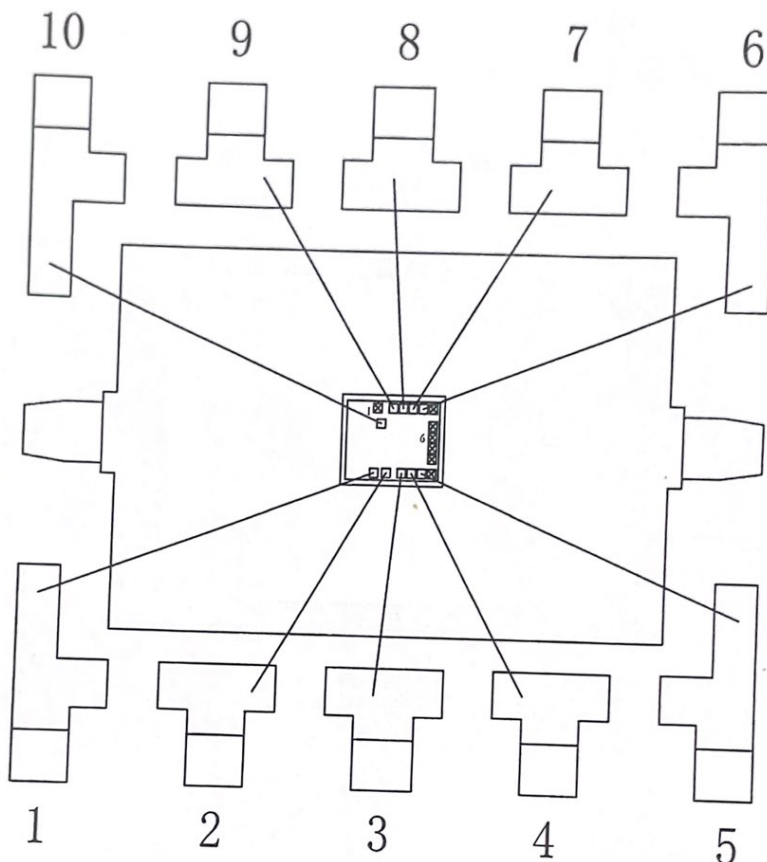
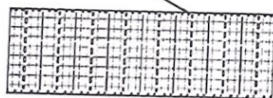


 池州华宇电子科技股份有限公司 CHIZHOU HISEMI ELECTRONICS TECHNOLOGY CO., LTD				客户代码 Customer No.	008	线号 Drawing No.	HY-PX-008-741 A	
焊线图 BONDING Diagram				产品名称 Product Type	HS9060PD		封装外型 PKG Type	ESSOP10L
焊线种类 Wire Type	焊线直径(μm) Wire Diameter	焊线根数 NO. of wire	焊线总长(μm) Total wire length	最长焊线长(μm) Longest wire length	最短焊线长(μm) Shortest wire length	密封料型号(绿色环保) Compound Type (Green)	LF载体尺寸 LF Pad Size	
合金丝 Ag	30	10	18944	2091	1245	优选(Preferrist): CEL-1702HF 特选(Upornast): BME-G630AY	ESSOP10L-8R (83*130mil) 2098*3302mm ²	
客户图号 Customer drawing NO.								



封装特选方向(张片):
L/F Direction (D/A):

椭圆孔



实物图:
Chip photo:

特殊说明 Special Instructions:

DB注意:
1. 芯片居中放置;
WB注意:
1. 数字力不打线pad点个数;

说明 Instruction	贴片胶类型 Epoxy type	芯片名称 Die name	芯片尺寸 Die Size	最小焊盘尺寸 Min BPO(μm ²)	最小焊盘间距 Min BPP(μm)	焊盘厚度(μm) Pad Thickness	焊盘下是否有电路 Circuit under Pad	划片通宽度 Street line (μm)	晶圆尺寸 Wafer Size	是否处 Laser Mark	减薄厚度 Grinding Thickness
A芯: DIE A	导电胶 (conductivity) S502	HS5122	554.8*433.2(μm ²) 21.84*17.06(mil ²)	50.35*50.35	60	1	是/Yes	60	8	否 NO	300
B芯: DIE B											
C芯: DIE C											
编制 Prepared by	刘林. 2024.3.11		制图日期 Create Date	2024/3/11		生效日期 Effective Date	客户确认签字/盖章: Customer Signature 刘林				
研发审核 R&D Check	刘林. 2024.3.11		产品工程审核 PE Check			批准 Approved by					

*温馨提示: 图纸为产品下线生产的唯一依据, 请认真确认, 我司依据您签字的图纸生产, 如因图纸错误产生不可估量损失, 谢谢!
*warm tip: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inevitable loss. Thank you